

TPS2511 USB Dedicated Charging Port Controller and Current Limiting Power Switch

1 Features

- Supports a USB DCP Shorting D+ Line to D– Line
- Supports a USB DCP Applying 2 V on D+ Line and 2.7 V on D– Line (or a USB DCP Applying 2.7 V on D+ Line and 2 V on D– Line)
- Supports a USB DCP Applying 1.2 V on D+ and D– Lines
- Automatically Switch D+ and D– Lines Connections for an Attached Device
- Hiccup Mode for Output Short-Circuit Protection
- Provides \overline{CS} Pin for USB Cable Compensation
- Programmable Current Limit (ILIM_SET Pin)
- Accurate $\pm 10\%$ Current Limit at 2.3 A (Typical)
- 70-m Ω (Typical) High-Side MOSFET
- Compatible With USB 2.0 and 3.0 Power Switch Requirements
- Operating Range: 4.5 V to 5.5 V
- Available in 8-Pin MSOP-PowerPAD™ Package

2 Applications

- Vehicle USB Power Chargers
- AC-DC Wall Adapter With USB Ports
- Other USB Chargers

3 Description

The TPS2511 device is a USB-dedicated charging port (DCP) controller and current-limiting power switch. An auto-detect feature monitors USB data line voltage, and automatically provides the correct electrical signatures on the data lines to charge compliant devices among the following dedicated charging schemes:

1. Divider DCP, required to apply 2.7 V and 2 V on the D+ and D– lines respectively or 2 V and 2.7 V on the D+ and D– lines respectively
2. BC1.2 DCP, required to short the D+ line to the D– line
3. 1.2 V on both D+ and D– lines

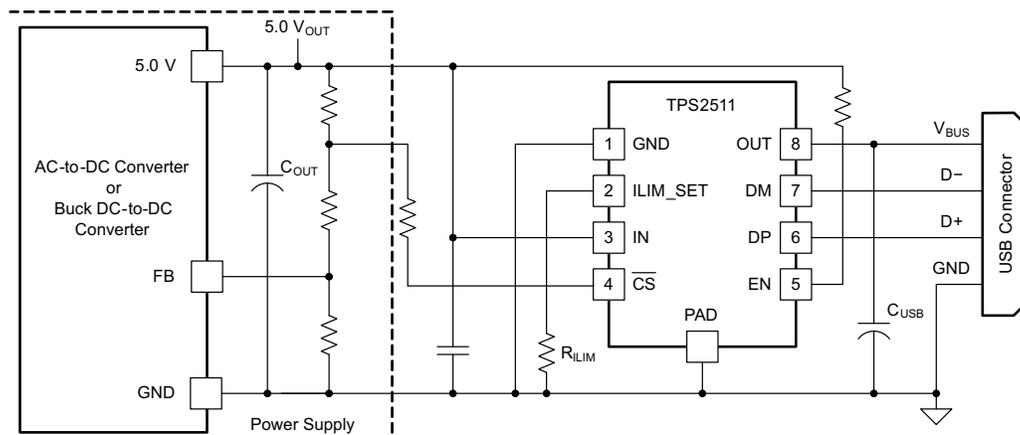
The TPS2511 is a 70-m Ω power-distribution switch intended for applications where heavy capacitive loads and short circuits are likely to be encountered. This device also provides hiccup mode when the output (OUT) voltage is less than 3.8 V (typical) or when an overtemperature protection occurs during an overload condition. Accurate and programmable current limit provides flexibility and convenience for applications. The TPS2511 provides a \overline{CS} pin for USB cable resistance compensation and an EN pin to control the device turnon and turnoff.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPS2511	MSOP-PowerPAD (8)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic



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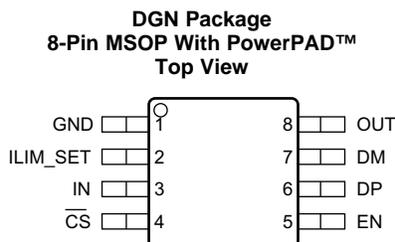
4 Revision History

Changes from Original (June 2012) to Revision A

Page

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section
- 1**
- Deleted *Ordering Information* table, see POA at the end of the document.....
- 1**

5 Pin Configuration and Functions



Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
\overline{CS}	4	O	Active-low, open-drain output. When OUT current is more than approximately half of the current limit set by a resistor on ILIM_SET pin, the output is active low. Maximum sink current is 10 mA.
DM	7	I/O	Connected to the D– or D+ line of USB connector. Provide the correct voltage with an attached portable equipment for DCP detection, high impedance while disabled.
DP	6	I/O	Connected to the D+ or D– line of USB connector. Provide the correct voltage with an attached portable equipment for DCP detection, high impedance while disabled.
EN	5	I	Logic-level control input. When it is high, turns power switch on, when it is low, turns power switch off and turns DP and DM into the high impedance state.
GND	1	G	Ground connection.
ILIM_SET	2	I	External resistor used to set current limiting Threshold. TI recommends $16.9\text{ k}\Omega \leq R_{ILIM_SET} \leq 750\text{ k}\Omega$.
IN	3	P	Power supply input voltage connected to the power switch. Connect a ceramic capacitor with a value of 0.1- μF or greater from the IN pin to GND as close to the device as possible.
OUT	8	O	Power-switch output. Connect to VBUS of USB
PowerPAD	PowerPAD	G	Ground connection.

(1) G = Ground, I = Input, O = Output, P = Power

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
Voltage	IN	Supply voltage	-0.3	7	V
	EN, ILIM_SET	Input voltage	-0.3	7	
	OUT, \overline{CS}		-0.3	7	
	IN to OUT		-7	7	
	DP output voltage	DM output	-0.3	IN+0.3 or 5.7	
	DP input voltage	DM input	-0.3	IN+0.3 or 5.7	
Current	DP input current, DM input current	Continuous output sink current		35	mA
	DP output current, DM output current	Continuous output source current		35	
	\overline{CS}	Continuous output sink current		10	
	ILIM_SET	Continuous output source current		Internally limited	
Temperature	Operating junction temperature, T _J		Internally limited		
	Storage temperature, T _{stg}		-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT	
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	All pins except 6 and 7	±2000	V
			Pins 6 and 7	±7500	
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾		±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

voltages are referenced to GND (unless otherwise noted), positive current are into pins.

			MIN	MAX	UNIT
V _{IN}	Input voltage of IN		4.5	5.5	V
V _{\overline{CS}}	Input voltage of \overline{CS}		0	5.5	
V _{EN}	Input voltage of EN		0	5.5	
V _{DP}	DP data line input voltage		0	5.5	
V _{DM}	DM data line input voltage		0	5.5	
I _{DP}	Continuous sink/source current			±10	mA
I _{DM}	Continuous sink/source current			±10	
I _{\overline{CS}}	Continuous sink current			2	
I _{OUT}	Continuous output current of OUT			2.2	A
R _{ILIM_SET}	A resistor of current limit, ILIM_SET to GND		16.9	750	kΩ
T _J	Operating junction temperature		-40	125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS2511	UNIT
		DGN (MSOP-PowerPAD)	
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	65.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	53.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	36.9	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	3.9	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	36.6	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	13.4	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

Conditions are $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$, $4.5\text{ V} \leq V_{IN} \leq 5.5\text{ V}$, $V_{EN} = V_{IN}$ and $R_{ILIM_SET} = 22.1\text{ k}\Omega$. Positive current are into pins. Typical values are at 25°C . All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SWITCH						
R _{DS(on)}	Static drain-source ON-state resistance	I _{OUT} = 2 A		70	120	mΩ
		I _{OUT} = 2 A, $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 85^{\circ}\text{C}$		70	105	
		I _{OUT} = 2 A, T _J = T _A = 25°C		70	84	
I _{REV}	Reverse leakage current	V _{OUT} = 5.5 V, V _{IN} = V _{EN} = 0 V		0.01	2	μA
DISCHARGE						
R _{DCHG}	Discharge resistance	V _{OUT} = 4 V	400	500	630	Ω
CURRENT LIMIT						
I _{OS}	OUT short-circuit current limit	R _{ILIM_SET} = 44.2 kΩ	1060	1160	1270	mA
		R _{ILIM_SET} = 22.1 kΩ	2110	2300	2550	
		R _{ILIM_SET} = 16.9 kΩ	2760	3025	3330	
HICCUP MODE						
V _{OUT_SHORT}	OUT voltage threshold of going into hiccup mode	V _{IN} = 5 V, R _{ILIM_SET} = 210 kΩ	3.6	3.8	4.1	V
UNDERVOLTAGE LOCKOUT						
V _{UVLO}	IN UVLO threshold voltage, rising		3.9	4.1	4.3	V
	Hysteresis ⁽¹⁾			100		mV
SUPPLY CURRENT						
I _{IN_OFF}	Disabled, IN supply current	V _{EN} = 0 V, V _{IN} = 5.5 V, $-40^{\circ}\text{C} \leq T_J \leq 85^{\circ}\text{C}$		0.1	2	μA
I _{IN_ON}	Enabled, IN supply current	V _{EN} = V _{IN} , R _{ILIM_SET} = 210 kΩ		180	230	
THERMAL SHUTDOWN						
	Temperature rising threshold ⁽¹⁾	Not in current limit		155		°C
		In current limit		135		
	Hysteresis ⁽¹⁾			10		
OUT CURRENT DETECTION						
I _{HCC_TH}	Load detection current threshold, rising ⁽¹⁾	R _{ILIM_SET} = 22.1 kΩ		1060		mA
		R _{ILIM_SET} = 44.2 kΩ		560		
I _{HCC_TH_HYS}	Load detection current Hysteresis ⁽¹⁾	R _{ILIM_SET} = 22.1 kΩ		230		mA
		R _{ILIM_SET} = 44.2 kΩ		120		
V _{CS}	CS output active-low voltage ⁽¹⁾	I _{CS} = 1 mA	0	80	140	mV

(1) Specified by design. Not production tested.

Electrical Characteristics (continued)

Conditions are $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$, $4.5\text{ V} \leq V_{\text{IN}} \leq 5.5\text{ V}$, $V_{\text{EN}} = V_{\text{IN}}$ and $R_{\text{ILIM_SET}} = 22.1\text{ k}\Omega$. Positive current are into pins. Typical values are at 25°C . All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ENABLE INPUT (EN)						
$V_{\text{EN_TRIP}}$	EN threshold voltage, falling		0.9	1.1	1.65	V
$V_{\text{EN_TRIP_HYS}}$	Hysteresis		100	200	300	mV
I_{EN}	Leakage current	$V_{\text{EN}} = 0\text{ V}$ or $V_{\text{EN}} = 5.5\text{ V}$	-0.5		0.5	μA
BC 1.2 DCP MODE (SHORT MODE)						
$R_{\text{DPM_SHORT}}$	DP and DM shorting resistance	$V_{\text{DP}} = 0.8\text{ V}$, $I_{\text{DM}} = 1\text{ mA}$		125	200	Ω
$R_{\text{DCHG_SHORT}}$	Resistance between DP/DM and GND	$V_{\text{DP}} = 0.8\text{ V}$	400	700	1300	$\text{k}\Omega$
$V_{\text{DPL_TH_DETACH}}$	Voltage threshold on DP under which the device goes back to divider mode		310	330	350	mV
$V_{\text{DPL_TH_DETACH_HYS}}$	Hysteresis			50 ⁽¹⁾		mV
DIVIDER MODE						
$V_{\text{DP_2.7V}}$	DP output voltage	$V_{\text{IN}} = 5\text{ V}$	2.57	2.7	2.84	V
$V_{\text{DM_2.0V}}$	DM output voltage	$V_{\text{IN}} = 5\text{ V}$	1.9	2	2.1	
$R_{\text{DP_PAD1}}$	DP output impedance	$I_{\text{DP}} = -5\text{ }\mu\text{A}$	24	30	40	$\text{k}\Omega$
$R_{\text{DM_PAD1}}$	DM output impedance	$I_{\text{DM}} = -5\text{ }\mu\text{A}$	24	30	40	
1.2 V / 1.2 V MODE						
$V_{\text{DP_1.2V}}$	DP output voltage	$V_{\text{IN}} = 5\text{ V}$	1.12	1.2	1.28	V
$V_{\text{DM_1.2V}}$	DM output voltage	$V_{\text{IN}} = 5\text{ V}$	1.12	1.2	1.28	V
$R_{\text{DP_PAD2}}$	DP output impedance	$I_{\text{DP}} = -5\text{ }\mu\text{A}$	80	105	130	$\text{k}\Omega$
$R_{\text{DM_PAD2}}$	DM output impedance	$I_{\text{DM}} = -5\text{ }\mu\text{A}$	80	105	130	$\text{k}\Omega$

6.6 Switching Characteristics

Conditions are $-40^{\circ}\text{C} \leq (T_J = T_A) \leq 125^{\circ}\text{C}$, $4.5\text{ V} \leq V_{\text{IN}} \leq 5.5\text{ V}$, $V_{\text{EN}} = V_{\text{IN}}$ and $R_{\text{ILIM_SET}} = 22.1\text{ k}\Omega$. Positive current are into pins. Typical values are at 25°C . All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SWITCH						
t_r	OUT voltage rise time	$C_L = 1\text{ }\mu\text{F}$, $R_L = 100\text{ }\Omega$, $V_{\text{IN}} = 5\text{ V}$ see Figure 1 , Figure 3		1	1.5	ms
t_f	OUT voltage fall time	$C_L = 1\text{ }\mu\text{F}$, $R_L = 100\text{ }\Omega$, $V_{\text{IN}} = 5\text{ V}$ see Figure 1 , Figure 3	0.2	0.35	0.5	
CURRENT LIMIT						
t_{IOS}	Short circuit response time ⁽¹⁾	$V_{\text{IN}} = 5\text{ V}$, $R_L = 50\text{ m}\Omega$, 2 inches lead length, See Figure 4		1.5		μs
HICCUP MODE						
$t_{\text{OS_DEG}}$	ON-time of hiccup mode ⁽¹⁾	$V_{\text{IN}} = 5\text{ V}$, $R_L = 0$		16		ms
$t_{\text{SC_TURN_OFF}}$	OFF-time of hiccup mode ⁽¹⁾	$V_{\text{IN}} = 5\text{ V}$, $R_L = 0$		12		s
OUT CURRENT DETECTION						
$t_{\text{CS_EN}}$	$\overline{\text{CS}}$ deglitch time during turning on ⁽¹⁾	$I_{\text{CS}} = 1\text{ mA}$		8		ms
ENABLE INPUT (EN)						
t_{on}	OUT voltage turnon time	$C_L = 1\text{ }\mu\text{F}$, $R_L = 100\text{ }\Omega$, see Figure 1 , Figure 2		2.6	5	ms
t_{off}	OUT voltage turnoff time			1.7	3	

(1) Specified by design. Not production tested.

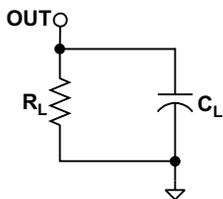


Figure 1. Output Rise and Fall Test Load

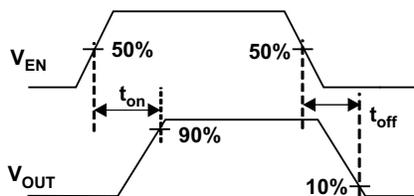


Figure 2. Enable Timing, Active High Enable

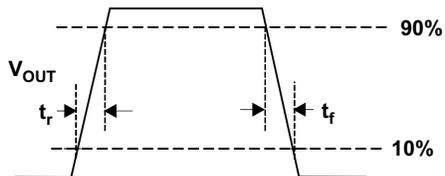


Figure 3. Power On and Power Off

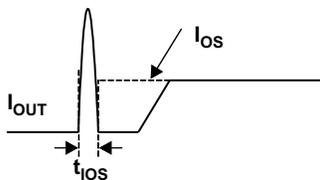


Figure 4. Output Short-Circuit Parameters

6.7 Typical Characteristics

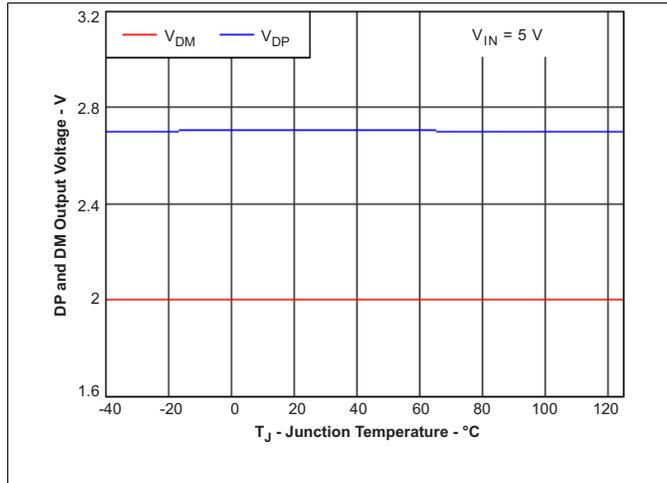


Figure 5. DP and DM Output Voltage vs Temperature

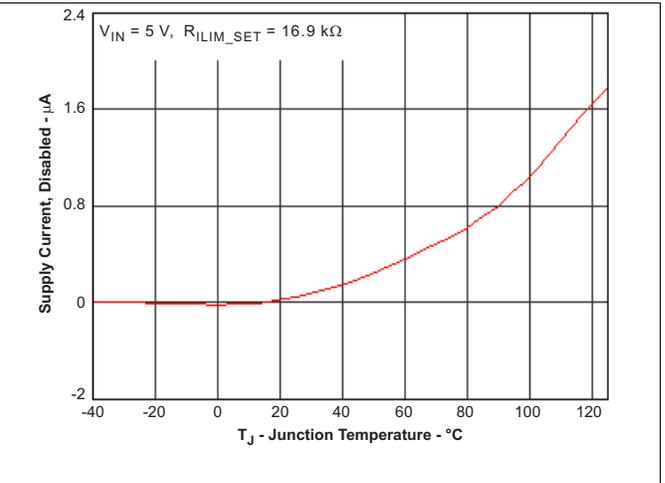


Figure 6. Supply Current Disabled vs Temperature

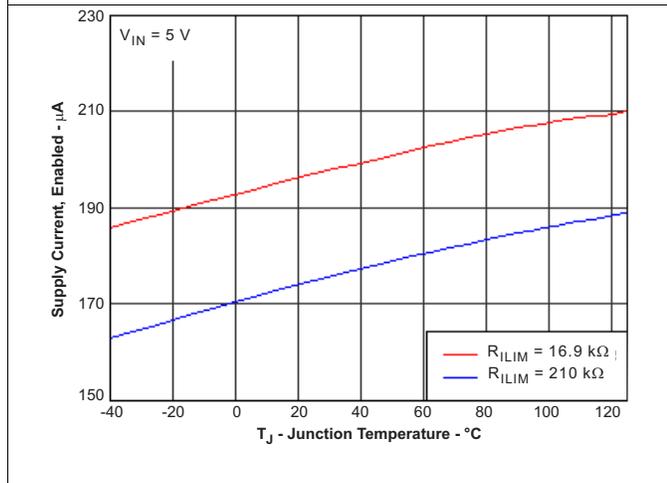


Figure 7. Supply Current Enabled vs Temperature

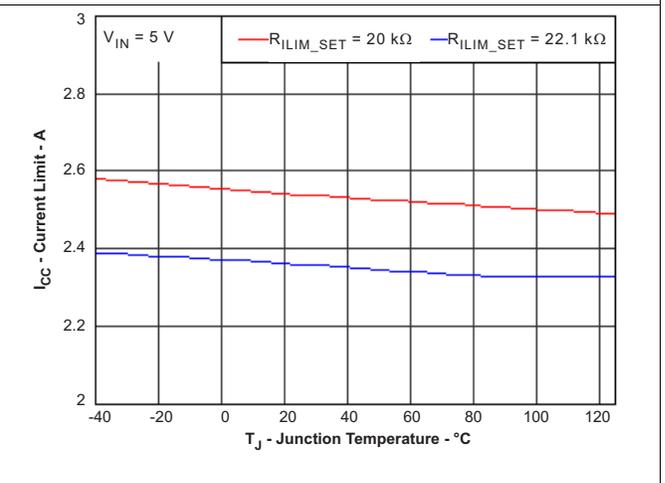


Figure 8. Current Limit vs Temperature

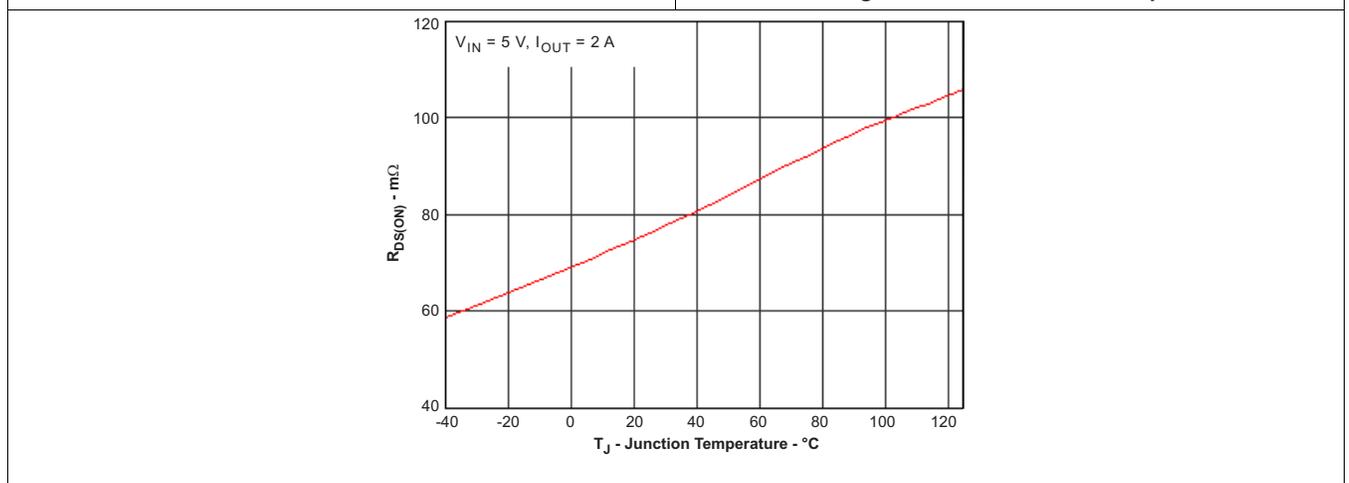


Figure 9. Power Switch ON-Resistance (R_{DS(ON)}) vs Temperature

7 Detailed Description

7.1 Overview

The following overview references various industry standards. TI always recommends consulting the latest standard to ensure the most recent and accurate information.

Rechargeable portable equipment requires an external power source to charge its batteries. USB ports are convenient locations for charging because of an available 5-V power source. Universally accepted standards are required to ensure host and client-side devices meet the power management requirements. Traditionally, USB host ports following the USB 2.0 Specification must provide at least 500 mA to downstream client-side devices. Because multiple USB devices can be attached to a single USB port through a bus-powered hub, it is the responsibility of the client-side device to negotiate the power allotment from the host to ensure the total current draw does not exceed 500 mA. The TPS2511 provides 100 mA of current to each USB device. Each USB device can subsequently request more current, which is granted in steps of 100 mA up 500 mA total. The host may grant or deny the request based on the available current.

Additionally, the success of the USB technology makes the micro-USB connector a popular choice for wall adapter cables. This allows a portable device to charge from both a wall adapter and USB port with only one connector.

One common difficulty has resulted from this. As USB charging has gained popularity, the 500-mA minimum defined by the USB 2.0 Specification or 900 mA defined in the USB 3.0 Specification, has become insufficient for many handsets, tablets, and personal media players (PMP), which have a higher-rated charging current. Wall adapters and car chargers can provide much more current than 500 mA or 900 mA to fast charge portable devices. Several new standards have been introduced defining protocol handshaking methods that allow host and client devices to acknowledge and draw additional current beyond the 500 mA (defined in the USB 2.0 Specification) or 900 mA (defined in the USB 3.0 Specification) minimum while using a single micro-USB input connector.

The TPS2511 supports three of the most common protocols:

- USB Battery Charging Specification, Revision 1.2 (BC1.2)
- Chinese Telecommunications Industry Standard YD/T 1591-2009
- Divider Mode

In these protocols there are three types of charging ports defined to provide different charging current to client-side devices. These charging ports are defined as:

- Standard downstream port (SDP)
- Charging downstream port (CDP)
- Dedicated charging port (DCP)

The BC1.2 Specification defines a charging port as a downstream facing USB port that provides power for charging portable equipment.

[Table 1](#) lists different port operating modes according to the BC1.2 Specification.

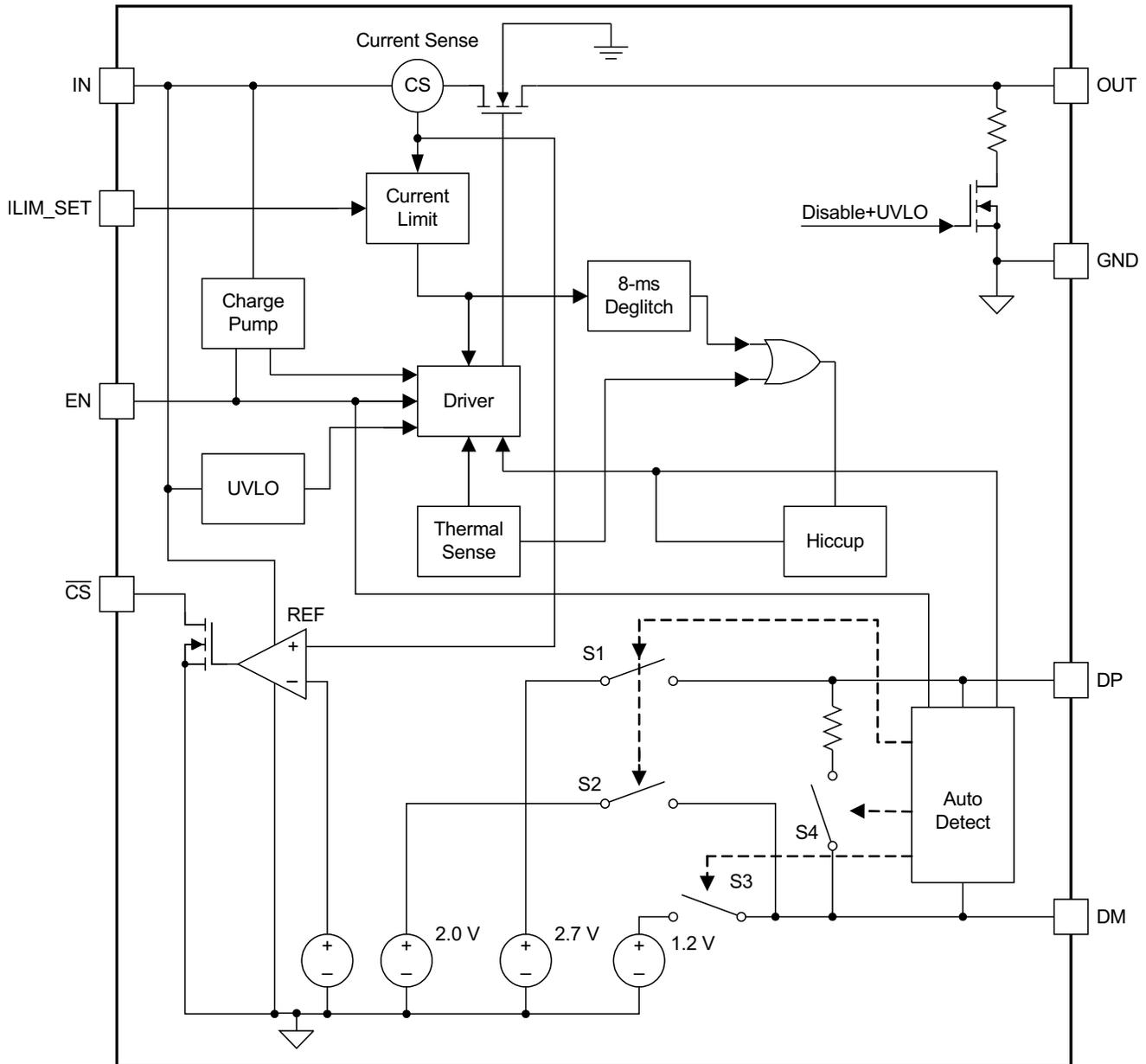
Table 1. Operating Modes Table

PORT TYPE	SUPPORTS USB 2.0 COMMUNICATION	MAXIMUM ALLOWABLE CURRENT DRAWN BY PORTABLE EQUIPMENT (A)
SDP (USB 2.0)	Yes	0.5
SDP (USB 3.0)	Yes	0.9
CDP	Yes	1.5
DCP	No	1.5

The BC1.2 Specification defines the protocol necessary to allow portable equipment to determine what type of port it is connected to so that it can allot its maximum allowable current drawn. The hand-shaking process is two steps. During step one, the primary detection, the portable equipment outputs a nominal 0.6-V output on its D+ line and reads the voltage input on its D– line. The portable device concludes it is connected to a SDP if the voltage is less than the nominal data detect voltage of 0.3 V. The portable device concludes that it is connected to a Charging Port if the D– voltage is greater than the nominal data detect voltage of 0.3 V and less than 0.8 V.

The second step, the secondary detection, is necessary for portable equipment to determine between a CDP and a DCP. The portable device outputs a nominal 0.6-V output on its D– line and reads the voltage input on its D+ line. The portable device concludes it is connected to a CDP if the data line being remains is less than the nominal data detect voltage of 0.3 V. The portable device concludes it is connected to a DCP if the data line being read is greater than the nominal data detect voltage of 0.3 V and less than 0.8 V.

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Overcurrent Protection

During an overload condition, the TPS2511 maintains a constant output current and reduces the output voltage accordingly. If the output voltage falls to less than 3.8 V for 16 ms, the TPS2511 turns off the output for a period of 12 seconds as shown in Figure 10. This operation is referred to as hiccup mode. The device stays in hiccup mode (power cycling) until the overload condition is removed. Therefore the average output current is significantly reduced to greatly improve the thermal stress of the device while the OUT pin is shorted.

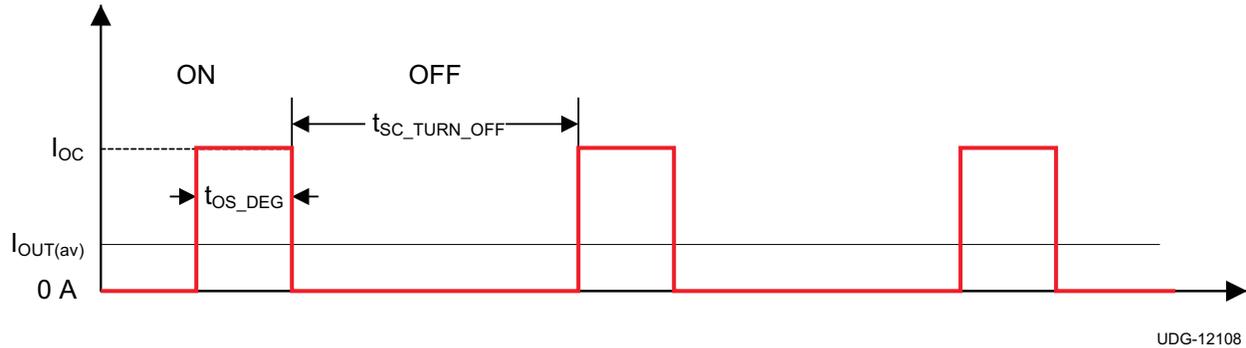


Figure 10. OUT Pin Short-Circuit Current in Hiccup Mode

Two possible overload conditions can occur. In the first condition, the output has been shorted before the device is enabled or before the voltage of IN has been applied. The TPS2511 senses the short and immediately switches into hiccup mode of constant-current limiting. In the second condition, a short or an overload occurs while the device is enabled. At the instant the overload occurs, high currents may flow for several microseconds before the current limit circuit can react. The device operates in constant-current mode for a period of 16 ms after the current limit circuit has responded, then switches into hiccup mode (power cycling).

Feature Description (continued)

7.3.2 Current Limit Threshold

The TPS2511 has a current limiting threshold that is externally programmed with a resistor. Equation 1 and Figure 11 help determine the typical current limit threshold.

$$I_{OS_TYP} = \frac{51228}{R_{ILIM}}$$

where

- I_{OS_TYP} is in mA and R_{ILIM} is in $k\Omega$
 - I_{OS_TYP} has a better accuracy if R_{ILIM} is less than 210 $k\Omega$
- (1)

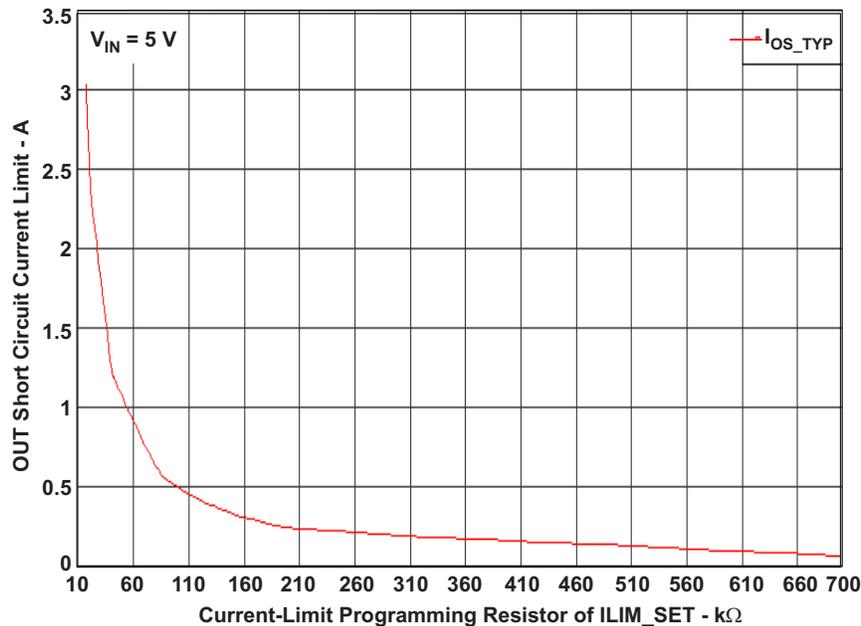


Figure 11. Typical Current Limit vs Programming Resistor

7.3.3 Current-Sensing Report (\overline{CS})

The \overline{CS} open-drain output is asserted immediately when the OUT pin current is more than about half of the current limit set by a resistor on ILIM_SET pin. Built-in hysteresis improves the ability to resist current noise on the OUT pin. The \overline{CS} output is active low. The recommended operating sink current is less than 2 mA and maximum sink current is 10 mA.

7.3.4 Undervoltage Lockout (UVLO) and Enable (EN)

The undervoltage lockout (UVLO) circuit disables the power switch and other functional circuits until the input voltage reaches the UVLO turnon threshold. Built-in hysteresis prevents unwanted oscillations on the output due to input voltage drop from large current surges.

The logic input of the EN pin disables all of the internal circuitry while maintaining the power switch off. A logic-high input on the EN pin enables the driver, control circuits, and power switch. The EN input voltage is compatible with both TTL and CMOS logic levels.

7.3.5 Soft Start, Reverse Blocking, and Discharge Output

The power MOSFET driver incorporates circuitry that controls the rise and fall times of the output voltage to limit large current and voltage surges on the input supply, and provides built-in soft-start functionality. The TPS2511 power switch blocks current from the OUT pin to the IN pin when turned off by the UVLO or disabled. The TPS2511 includes an output discharge function. A 500- Ω (typical) discharge resistor dissipates stored charge and leakage current on the OUT pin when the device is in UVLO or disabled. However as this circuit is biased from the IN pin, the output discharge is not active when the input approaches 0 V.

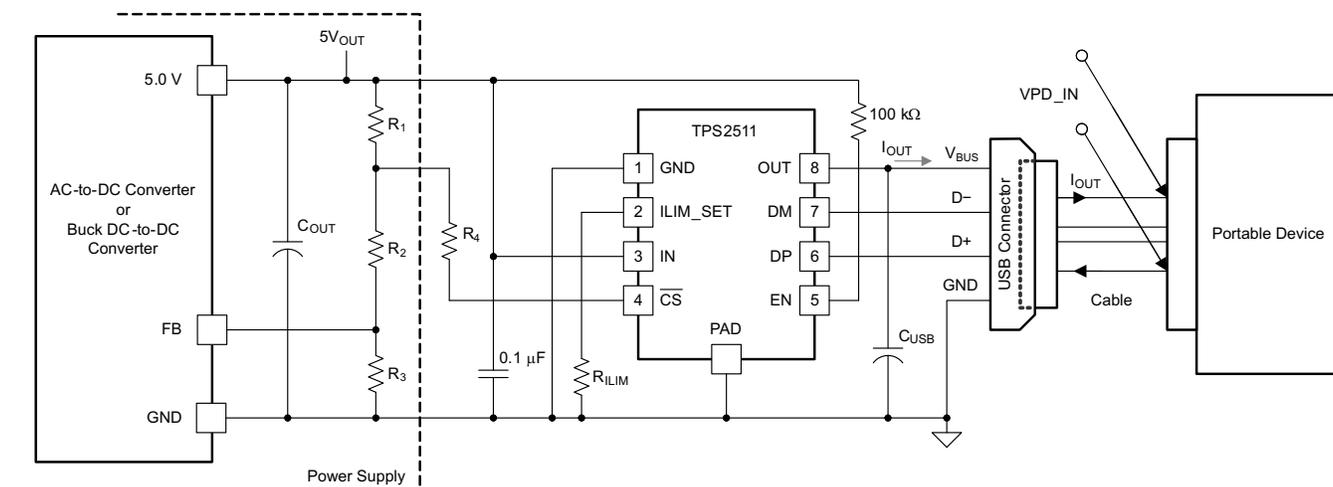
Feature Description (continued)

7.3.6 Thermal Sense

The TPS2511 provides thermal protection from two independent thermal-sensing circuits that monitor the operating temperature of the power distribution switch and turnoff for 12 s (typical) if the temperature exceeds recommended operating conditions. The device operates in constant-current mode during an overcurrent condition and OUT pin voltage is greater than 3.8 V (typical), which has a relatively large voltage drop across power switch. The power dissipation in the package is proportional to the voltage drop across the power switch, so the junction temperature rises during the overcurrent condition. The first thermal sensor turns off the power switch when the die temperature exceeds 135°C and the device is within the current limit. The second thermal sensor turns off the power switch when the die temperature exceeds 155°C regardless of whether the power switch is in current limit. Hysteresis is built into both thermal sensors, and the switch turns on after the device has cooled approximately 10°C. The switch continues to cycle off and on until the fault is removed.

7.3.7 V_{BUS} Voltage Drop Compensation

Figure 12 shows a USB charging design using the TPS2511. In general, V_{BUS} has some voltage loss due to USB cable resistance and TPS2511 power switch ON-state resistance. The sum of voltage loss is likely several hundred millivolts from $5-V_{OUT}$ to V_{PD_IN} that is the input voltage of PD while the high charging current charges the PD. For example, in Figure 13, assuming that the loss resistance is 170 mΩ (includes 100 mΩ of USB cable resistance and 70 mΩ of power switch resistance) and $5 V_{OUT}$ is 5 V, the input voltage of PD (V_{PD_IN}) is about 4.66 V at 2 A (see Figure 13).



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Figure 12. TPS2511 Charging System Schematic Diagram

The charging current of most portable devices is less than their maximum charging current while V_{PD_IN} is less than the certain voltage value. Furthermore, actual charging current of PD decreases with input voltage falling. Therefore, a portable devices cannot accomplish a fast charge with its maximum charging rated current if V_{BUS} voltage drop across the power path is not compensated at the high charging current. The TPS2511 provides CS pin to report the high charging current for USB chargers to increase the $5-V_{OUT}$ voltage. This is shown by the solid lines of Figure 13.

Feature Description (continued)

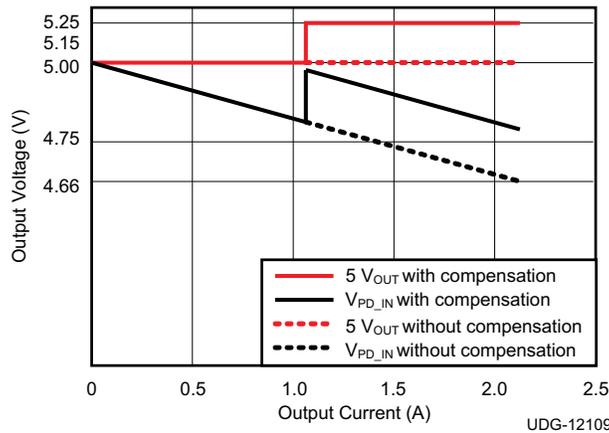


Figure 13. TPS2511 \overline{CS} Function

Equation 2 through Equation 5 refer to Figure 12.

The power supply output voltage is calculated in Equation 2.

$$5V_{OUT} = \frac{(R_1 + R_2 + R_3) \times V_{FB}}{R_3} \tag{2}$$

5 V_{OUT} and V_{FB} are known. If R₃ is given and R₁ is fixed, R₂ can be calculated. The 5 V_{OUT} voltage change with compensation is shown in Equation 3 and Equation 4.

$$\Delta V = \frac{(R_2 + R_3) \times R_1 \times V_{FB}}{R_3 \times R_4} \tag{3}$$

$$\Delta V = \left(\frac{5V_{OUT}}{V_{FB}} - \frac{R_1}{R_3} \right) \frac{R_1 \times V_{FB}}{R_4} \tag{4}$$

If R₁ is less than R₃, then Equation 4 can be simplified as Equation 5.

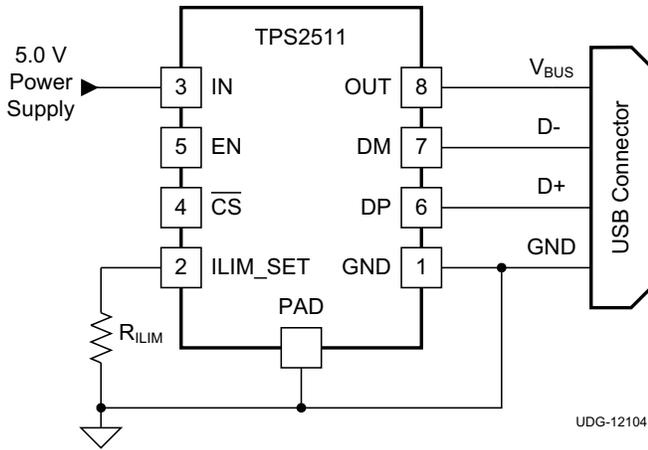
$$\Delta V \approx \frac{5V_{OUT} \times R_1}{R_4} \tag{5}$$

7.3.8 Divide Mode Selection of 5-W and 10-W USB Chargers

The TPS2511 provides two types of connections between the DP pin and the DM pin and between the D+ data line and the D– data line of the USB connector for a 5-W USB charger and a 10-W USB charger with a single USB port. For a 5-W USB charger, the DP pin is connectd to the D– line and the DM pin is connected to the D+ line. This is shown in Figure 16 and Figure 17. It is necessary to apply DP and DM to D+ and D– of USB connector for 10-W USB chargers. See Figure 14 and Figure 15. Table 2 shows different charging schemes for both 5-W and 10-W USB charger solutions

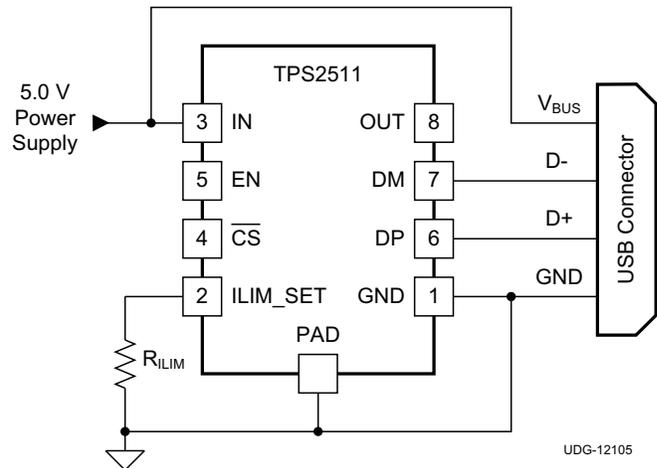
Table 2. Charging Schemes for 5-W and 10-W USB Chargers

USB CHARGER TYPE	CONTAINING CHARGING SCHEMES		
5-W	Divider1	1.2 V on both D+ and D– Lines	BC1.2 DCP
10-W	Divider2	1.2 V on both D+ and D– Lines	BC1.2 DCP



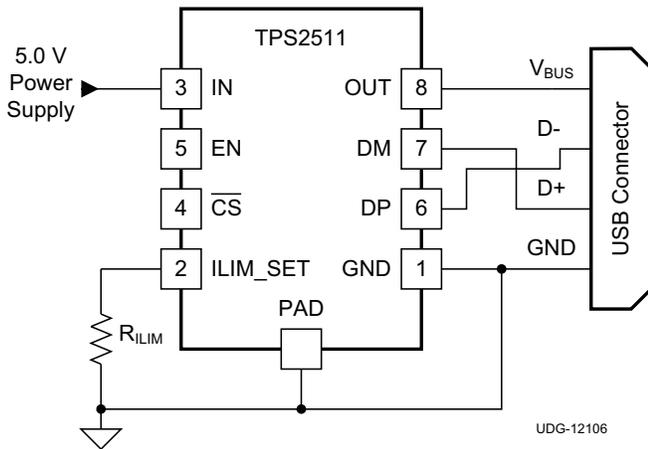
UDG-12104

Figure 14. 10-W USB Charger Application With Power Switch



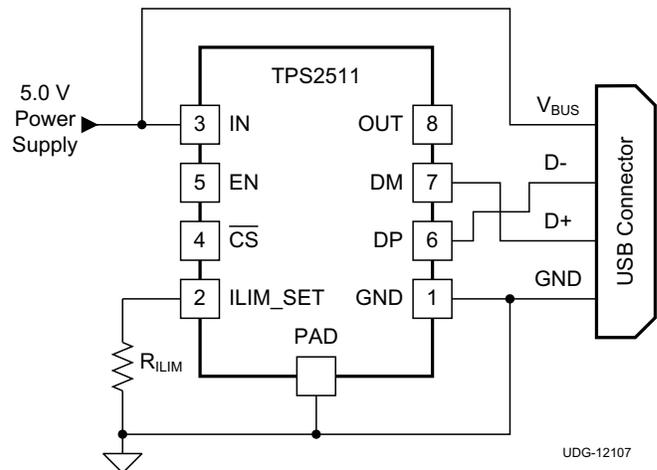
UDG-12105

Figure 15. 10-W USB Charger Application Without Power Switch



UDG-12106

Figure 16. 5-W USB Charger Application With Power Switch



UDG-12107

Figure 17. 5-W USB Charger Application Without Power Switch

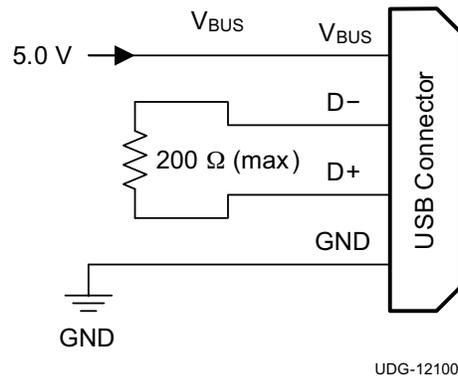
7.4 Device Functional Modes

7.4.1 Dedicated Charging Port (DCP)

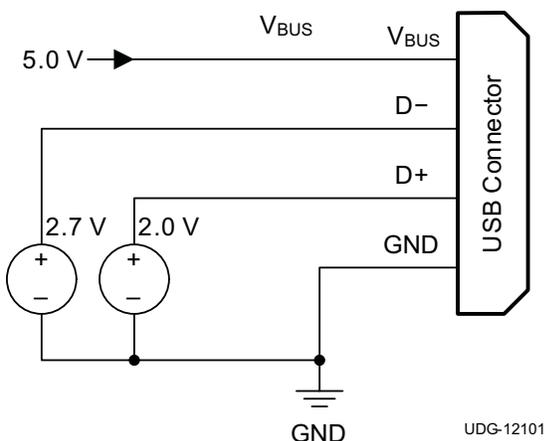
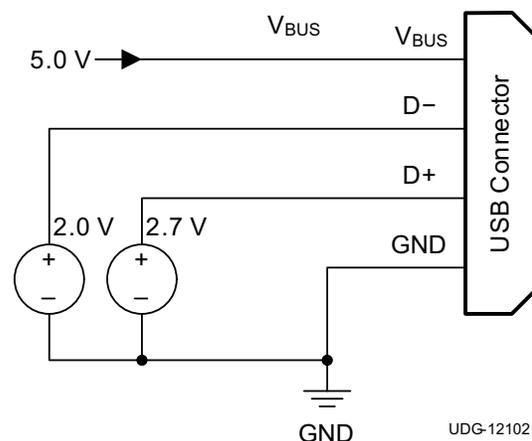
A dedicated charging port (DCP) is a downstream port on a device that outputs power through a USB connector, but is not capable of enumerating a downstream device, which generally allows portable devices to fast charge at their maximum rated current. A USB charger is a device with a DCP, such as a wall adapter or car power adapter. A DCP is identified by the electrical characteristics of its data lines. The following DCP identification circuits are usually used to meet the handshaking detections of different portable devices.

7.4.1.1 Short the D+ Line to the D– Line

The USB BC1.2 Specification and the Chinese Telecommunications Industry Standard YD/T 1591-2009 define that the D+ and D– data lines must be shorted together with a maximum series impedance of 200 Ω . This is shown in [Figure 18](#).

Device Functional Modes (continued)

Figure 18. DCP Short Mode
7.4.1.2 Divider1 (DCP Applying 2 V on D+ Line and 2.7 V on D– Line) or Divider2 (DCP Applying 2.7 V on D+ Line and 2 V on D– Line)

There are two charging schemes for divider DCP. They are named after Divider1 and Divider2 DCPs that are shown in [Figure 19](#) and [Figure 20](#). The Divider1 charging scheme is used for 5-W adapters, Divider1 applies 2 V to the D+ line and 2.7 V to the D– data line. The Divider2 charging scheme is used for 10-W adapters and applies 2.7 V on the D+ line and 2 V is applied on the D– line.


Figure 19. Divider1 DCP

Figure 20. Divider2 DCP
7.4.1.3 Applying 1.2 V to the D+ Line and 1.2 V to the D– Line

As shown in [Figure 21](#), some tablet USB chargers require 1.2 V on the shorted data lines of the USB connector. The maximum resistance between the D+ line and the D– line is 200 Ω .

Device Functional Modes (continued)

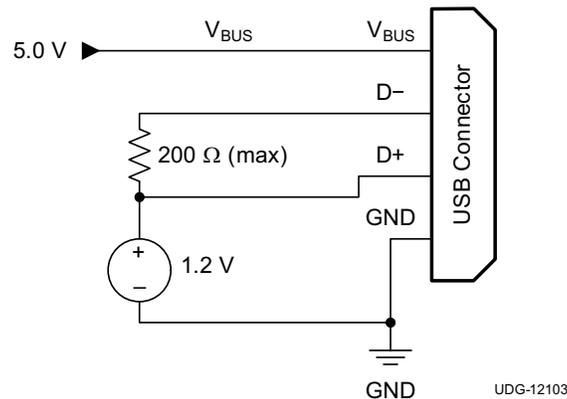


Figure 21. DCP Applying 1.2 V to the D+ Line and 1.2 V to the D– Line

The TPS2511 is a combination of a current-limiting USB power switch and an USB DCP identification controller. Applications include vehicle power charger, wall adapters with USB DCP and other USB chargers. The TPS2511 DCP controller has the auto-detect feature that monitors the D+ and D– line voltages of the USB connector, providing the correct electrical characteristics on the DP and DM pins for the correct detections of compliant portable devices to fast charge. These portable devices include smart phones, 5-V tablets, and personal media players.

The TPS2511 power-distribution switch is intended for applications where heavy capacitive loads and short circuits are likely to be encountered, incorporating a 70-mΩ, N-channel MOSFET in a single package. This device provides hiccup mode when in current limit and OUT voltage is less than 3.8 V (typical) or an over-temperature protection occurs under an overload condition. Hiccup mode operation can reduce the output short-circuit current down to several milliamperes. The TPS2511 provides a logic-level enable EN pin to control the device turnon and turnoff and an open-drain output CS for compensating V_{BUS} to account for cable $I \times R$ voltage loss.

7.4.2 DCP Auto-Detect

The TPS2511 integrates an *auto-detect* feature to support divider mode, short mode and 1.2 V / 1.2 V mode. If a divider device is attached, 2.7 V is applied to the DP pin and 2 V is applied to the DM pin. If a BC1.2-compliant device is attached, the TPS2511 automatically switches into short mode. If a device compliant with the 1.2 V / 1.2 V charging scheme is attached, 1.2 V is applied on both the DP pin and the DM pin. The functional diagram of DCP auto-detect feature is shown in [Figure 22](#).

Device Functional Modes (continued)

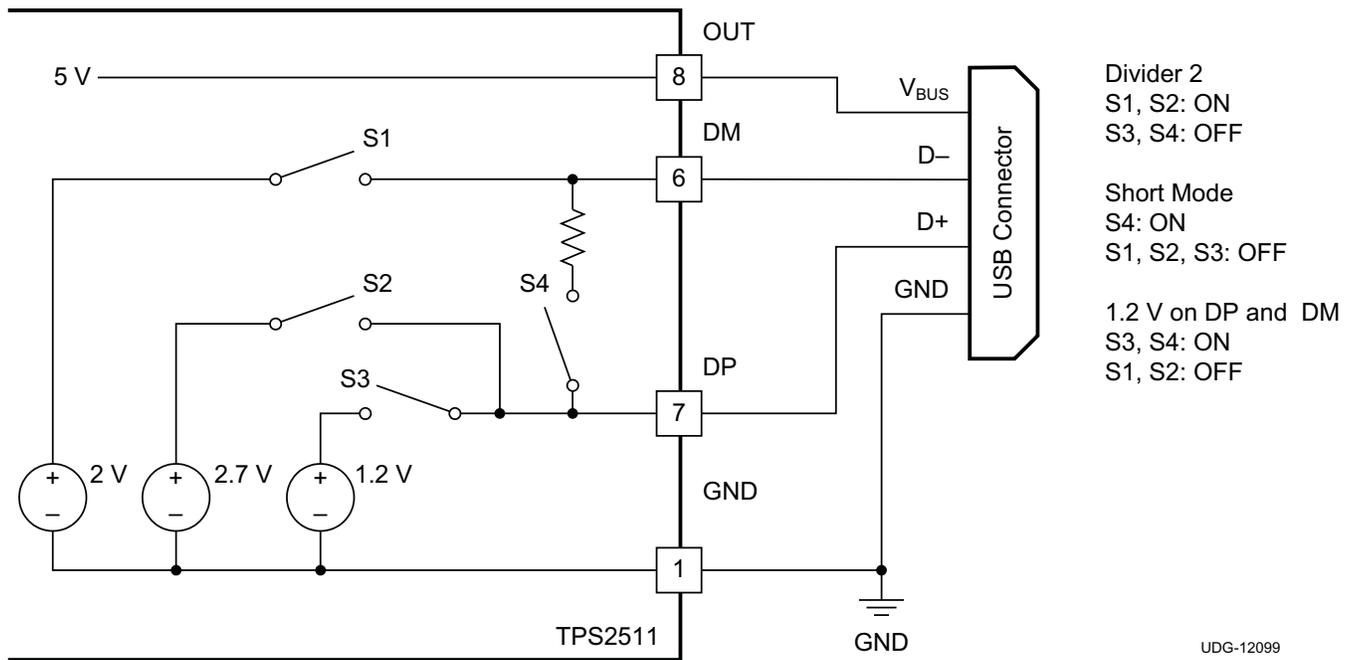


Figure 22. TPS2511 DCP Auto-Detect Functional Diagram

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPS2511 is a USB-dedicated charging-port controller and power switch with cable compensation. It is typically used for wall adapter or power bank as a USB charging controller and overcurrent protector.

8.2 Typical Application

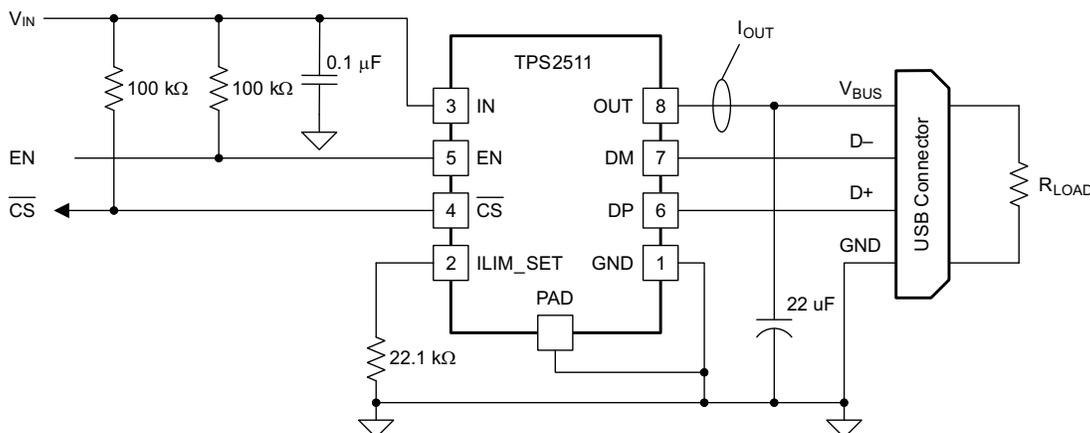


Figure 23. Test Circuit for System Operation

8.2.1 Design Requirements

For this design example, request IOS; Minimum must exceed 2100 mA.

When choosing the power switch, TI recommends following these general steps:

1. Determine the voltage of the power rail, 3.3 V or 5 V, and then choose the operation range of power switch can cover power rail.
2. Determine the normal operation current; for example, the maximum allowable current drawn by portable equipment for USB 2.0 port is 500 mA, so the normal operation current is 500 mA and the minimum current limit of power switch must exceed 500 mA to avoid false trigger during normal operation.
3. Determine the maximum allowable current provided by up-stream power, and then decide the maximum current limit of power switch that must lower it to ensure power switch can protect the up-stream power when overload is encountered at the output of power switch.

NOTE

Choosing power switch with tighter current limit tolerance can loosen the up-stream power supply design.

8.2.2 Detailed Design Procedure

The user-programmable R_{ILIM} resistor on the ILIMIT_SET pin sets the current limit. The TPS2511 uses an internal regulation loop to provide a regulated voltage on the ILIM_SET pin. The current limiting threshold is proportional to the current sourced out of the ILIM_SET pin. The recommended 1% resistor range for R_{ILIM} is from 16.9 kΩ to 750 kΩ to ensure stability of the internal regulation loop, although not exceeding 210 kΩ results in a better accuracy. Many applications require that the minimum current limit remain above a certain current

Typical Application (continued)

level or that the maximum current limit remain below a certain current level, so it is important to consider the tolerance of the overcurrent threshold when selecting a value for R_{ILIM} . Equation 6 and Equation 7 calculate the resulting overcurrent thresholds for a given external resistor value (R_{ILIM}). The traces routing the R_{ILIM} resistor to the TPS2511 must be as short as possible to reduce parasitic effects on the current limit accuracy. The equations along with Figure 24 and Figure 25 can be used to estimate the minimum and maximum variation of the current limit threshold for a predefined resistor value. This variation disregards the inaccuracy of the resistor itself.

$$I_{OS_MIN} = \frac{51228}{R_{ILIM}^{1.030}}$$

where

- I_{OS_MIN} is in mA
- R_{ILIM} is in $k\Omega$

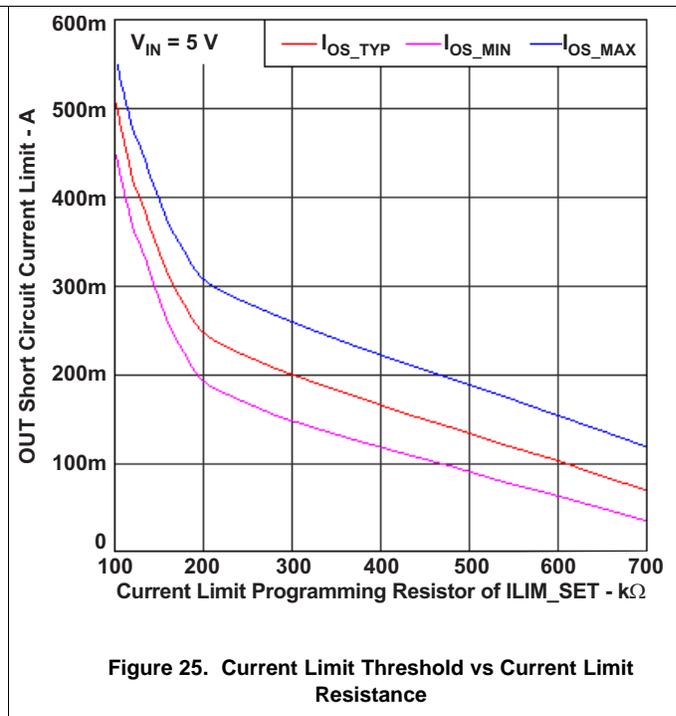
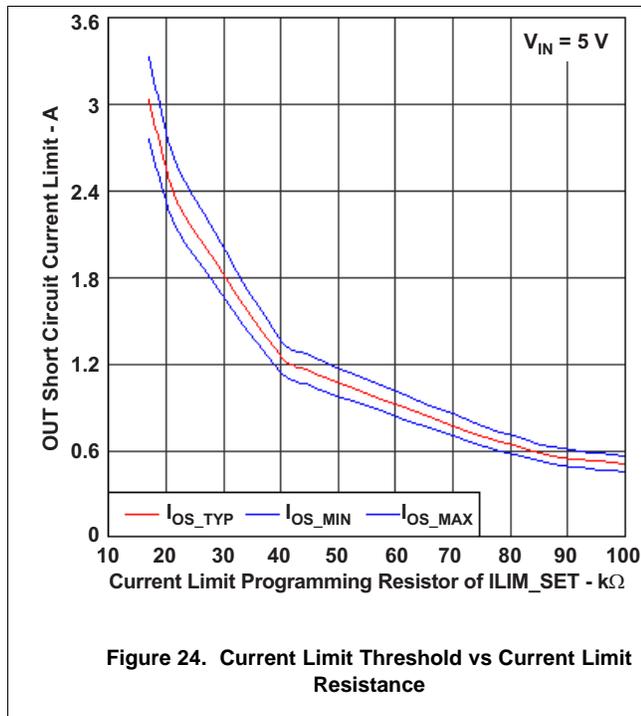
(6)

$$I_{OS_MAX} = \frac{51228}{R_{ILIM}^{0.967}}$$

where

- I_{OS_MAX} is in mA
- R_{ILIM} is in $k\Omega$

(7)



For this example design, as shown in Equation 8, $I_{OS_MIN} = 2100$ mA.

$$I_{OS_MIN} = \frac{51228}{R_{ILIM}^{1.03}} = 2100 \text{ mA}$$

(8)

$$R_{ILIM} = \left(\frac{51228}{I_{OS_MIN}} \right)^{\frac{1}{1.03}} = \left(\frac{51228}{2100} \right)^{\frac{1}{1.03}} = 22.227 \text{ k}\Omega$$

(9)

Typical Application (continued)

Including resistor tolerance, target nominal resistance value given by Equation 10.

$$R_{ILIM} = \frac{22.227 \text{ k}\Omega}{1.01 \text{ k}\Omega} = 22.007 \text{ k}\Omega \quad (10)$$

Choose Equation 11.

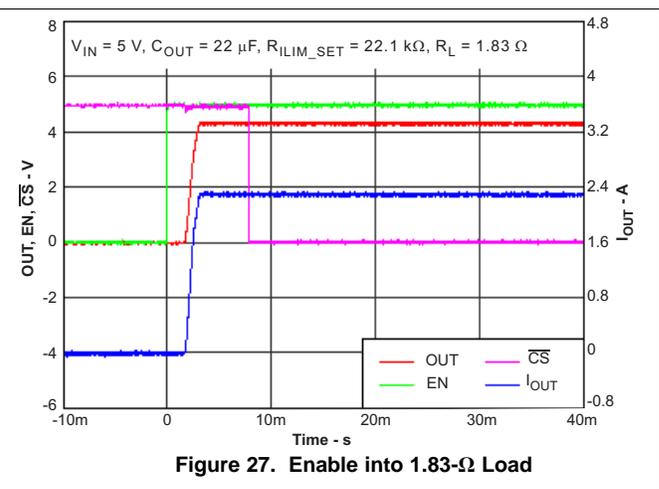
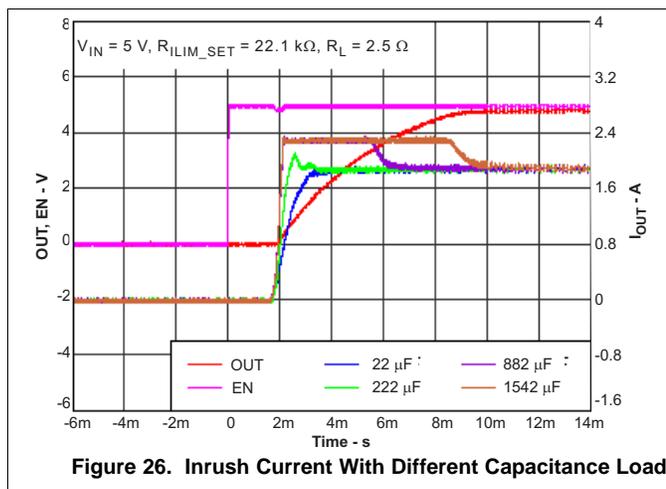
$$R_{ILIM} = 22 \text{ k}\Omega \quad (11)$$

8.2.2.1 Input and Output Capacitance

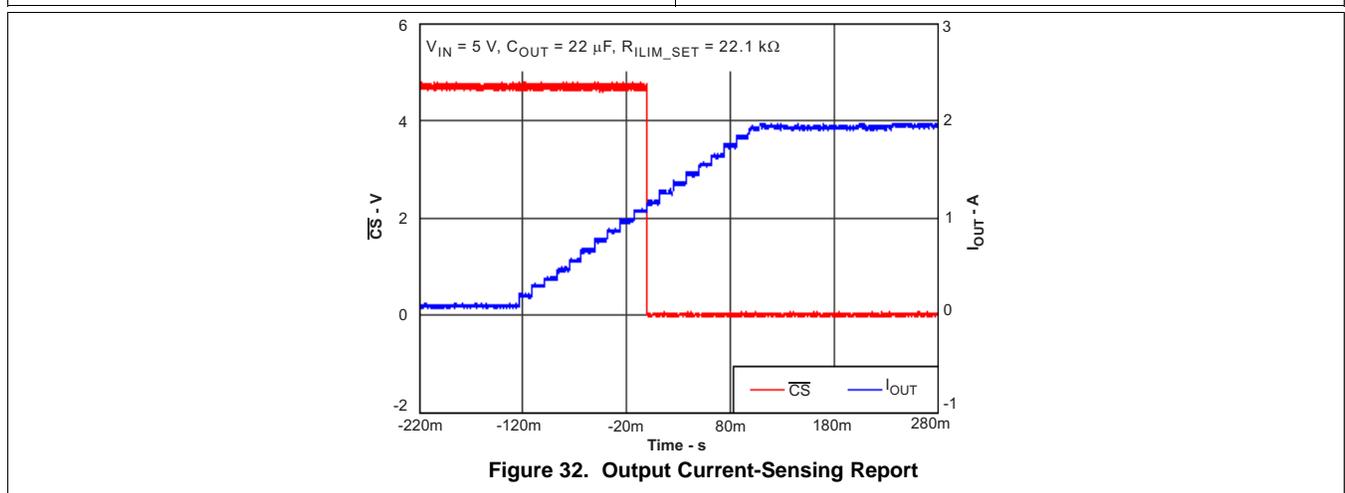
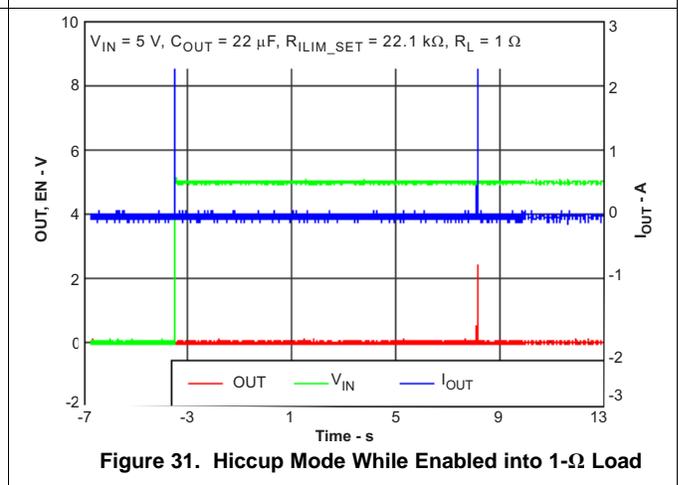
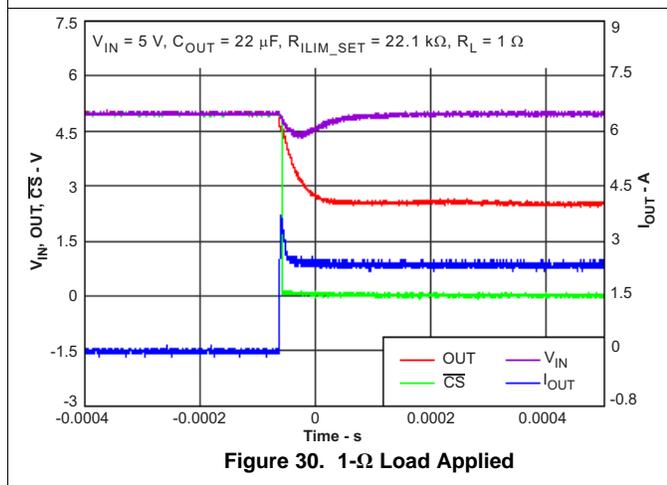
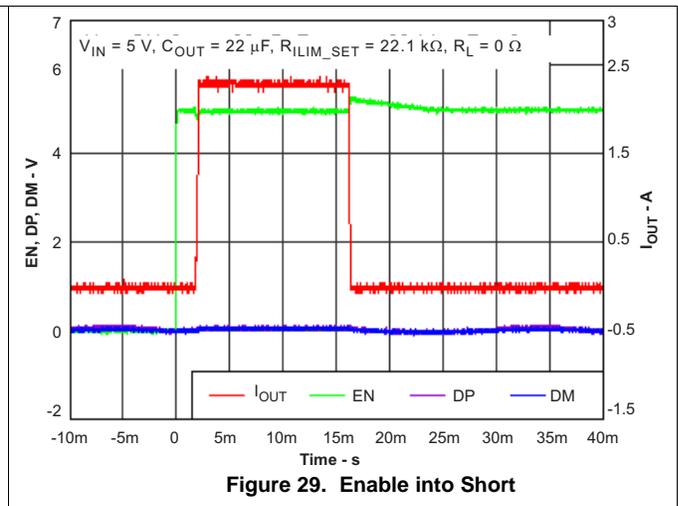
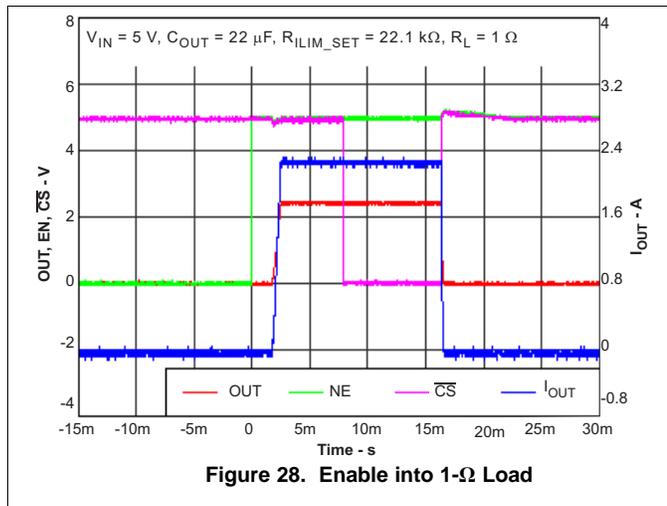
Input and output capacitance improves the performance of the device; the actual capacitance must be optimized for the particular application. For all applications, TI recommends placing a 0.1- μF or greater ceramic bypass capacitor between IN and GND, as close to the device as possible for local noise decoupling. This precaution reduces ringing on the input due to power-supply transients. Additional input capacitance may be needed on the input to reduce voltage undershoot from exceeding the UVLO of other load share one power rail with TPS2511 or overshoot from exceeding the absolute-maximum voltage of the device during heavy transient conditions. This is especially important during bench testing when long, inductive cables are used to connect the evaluation board to the bench power supply.

TI recommends placing at least a 22- μF ceramic capacitor or higher-value electrolytic capacitor on the output pin when large transient currents are expected on the output to reduce the undershoot, which is caused by the inductance of the output power bus just after a short has occurred and the TPS2511 has abruptly reduced OUT current. Energy stored in the inductance drives the OUT voltage down and potentially negative as it discharges.

8.2.3 Application Curves



Typical Application (continued)



9 Power Supply Recommendations

Design of the devices is for operation from an input voltage supply range of 4.5 V to 5.5 V. The current capability of the power supply must exceed the maximum current limit of the power switch.

10 Layout

10.1 Layout Guidelines

- **TPS2511 placement.** Place the TPS2511 near the USB output connector and at least 22- μ F OUT pin filter capacitor. Connect the exposed PowerPAD to the GND pin and to the system ground plane using a via array.
- **IN pin bypass capacitance.** Place the 0.1- μ F bypass capacitor near the IN pin and make the connection using a low-inductance trace.
- **ILIM_SET pin connection.** Current limit setpoint accuracy can be compromised by stray leakage from a higher voltage source to the ILIM_SET pin. Ensure that there is adequate spacing between IN pin copper or trace and ILIM_SET pin trace to prevent contaminant buildup during the PCB assembly process. The traces routing the R_{ILIM} resistor to the device must be as short as possible to reduce parasitic effects on the current limit accuracy.
- **DP and DM consideration.** Route these traces as differential micro-strips. For DP and DM, there is no internal IEC ESD cell, refer to application note [Effective System ESD Protection Guidelines:TPS251x USB Charging Port Controllers](#) for these 2 pins' IEC ESD design guideline.

10.2 Layout Example

For the trace routing of DP and DM, no strictly request must route these traces as micro-strips with nominal differential impedance of $90\ \Omega$ because no USB 2.0 high-speed data transmission on these data line. But because there is no internal IEC ESD cell, TI recommends placing IEC ESD cell on DP and DM trace close to USB connector.

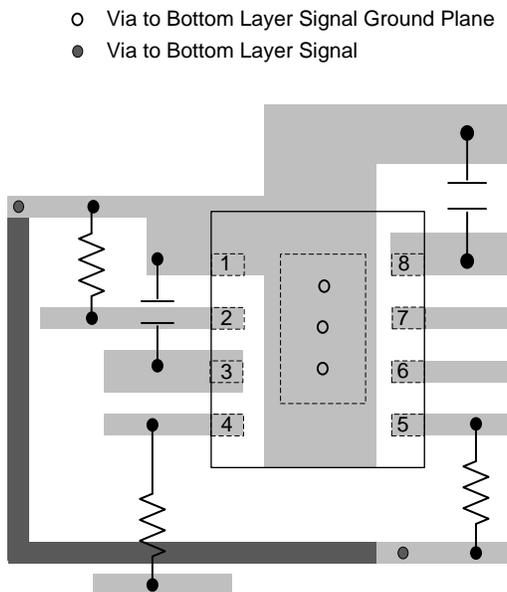


Figure 33. Layout Recommendation

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

[Effective System ESD Protection Guidelines:TPS251x USB Charging Port Controllers](#) (SLVA800)

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

PowerPAD, E2E are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS2511DGN	ACTIVE	MSOP-PowerPAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	2511	Samples
TPS2511DGNR	ACTIVE	MSOP-PowerPAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	2511	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

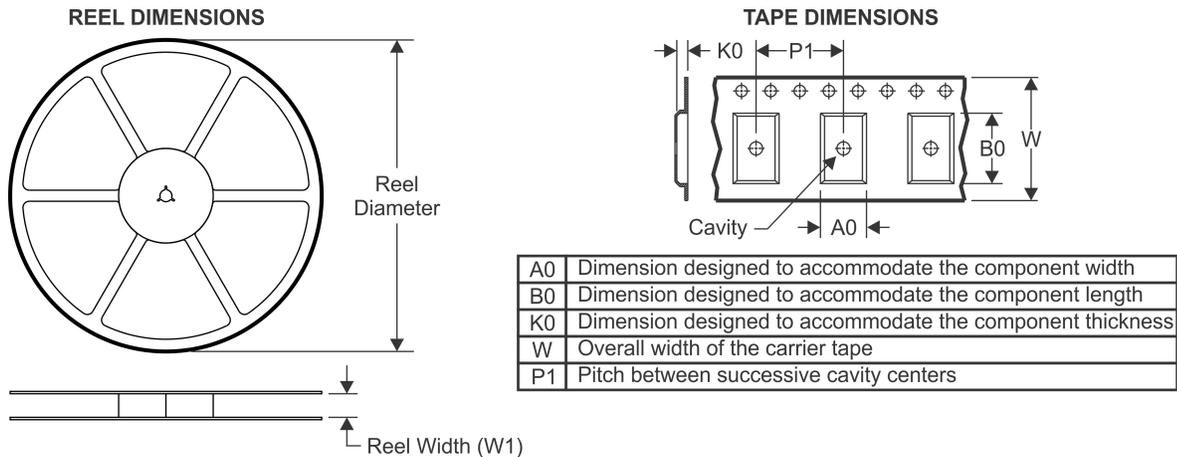
OTHER QUALIFIED VERSIONS OF TPS2511 :

- Automotive: [TPS2511-Q1](#)

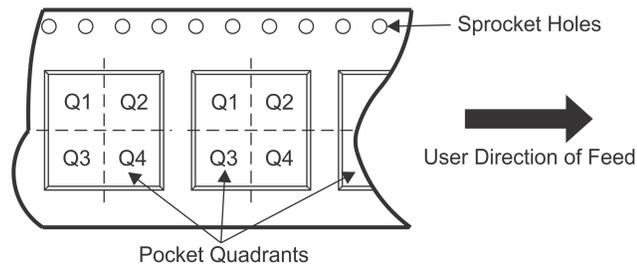
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



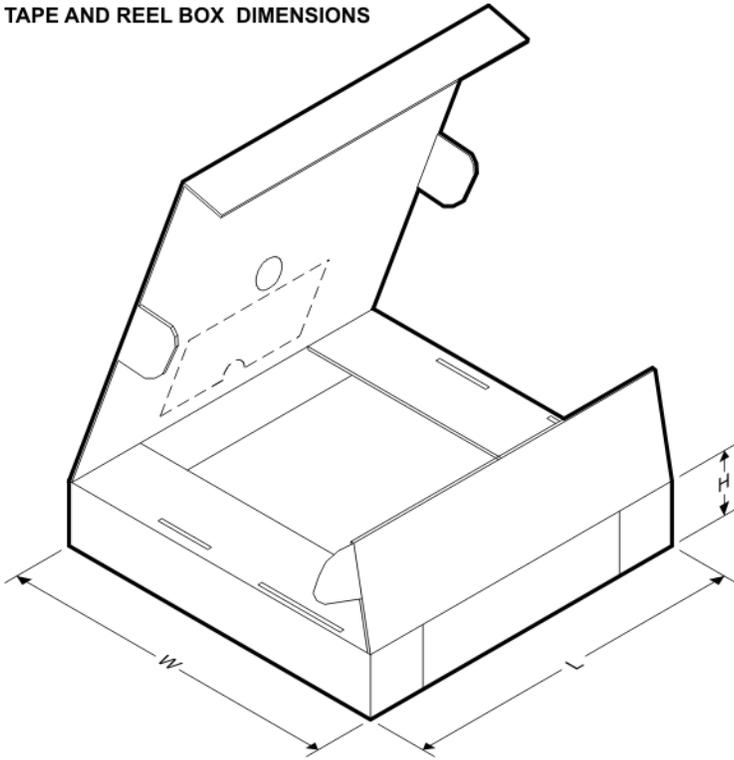
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS2511DGNR	MSOP-Power PAD	DGN	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

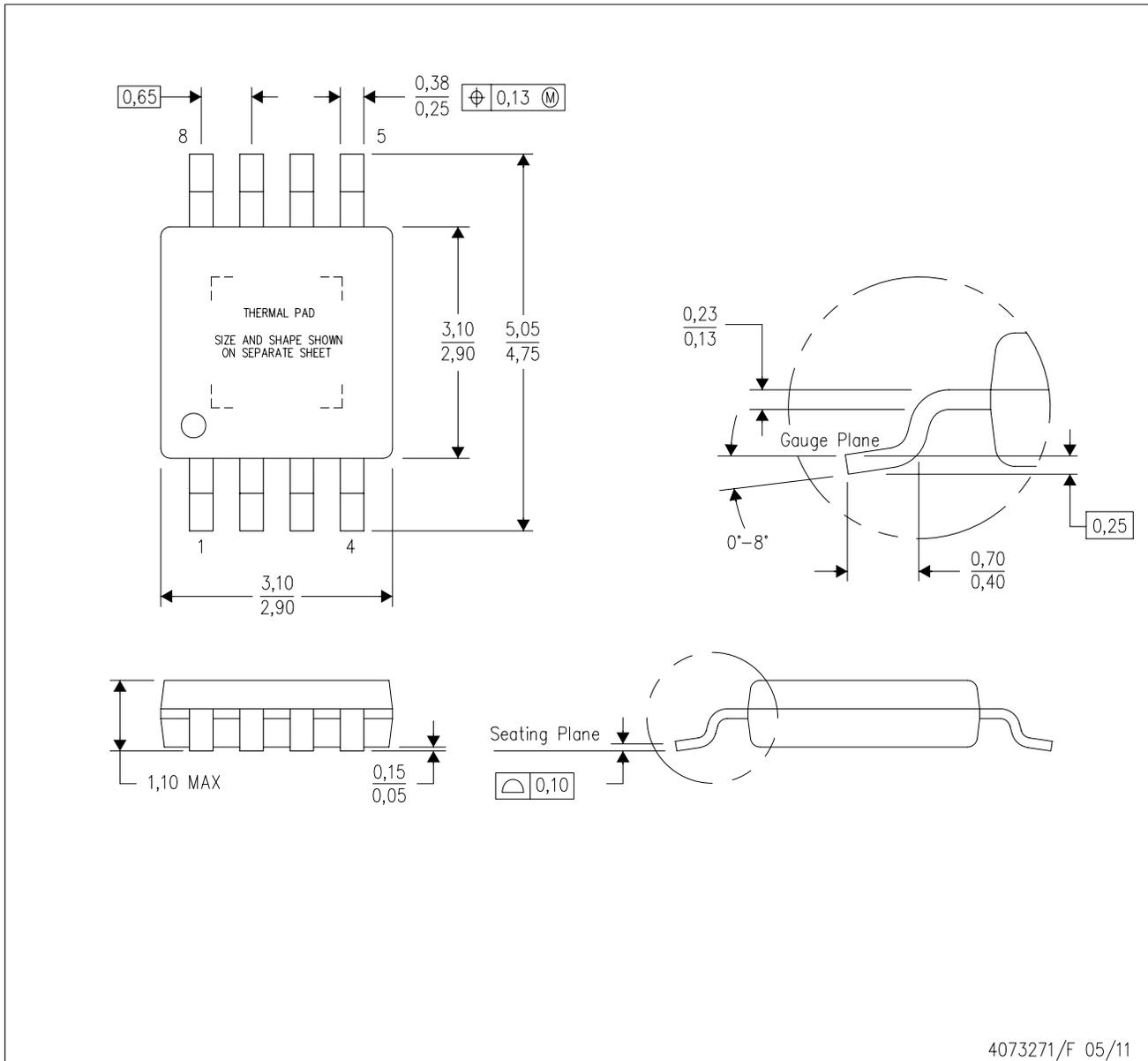


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS2511DGNR	MSOP-PowerPAD	DGN	8	2500	366.0	364.0	50.0

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-187 variation AA-T

PowerPAD is a trademark of Texas Instruments.

THERMAL PAD MECHANICAL DATA

DGN (S-PDSO-G8)

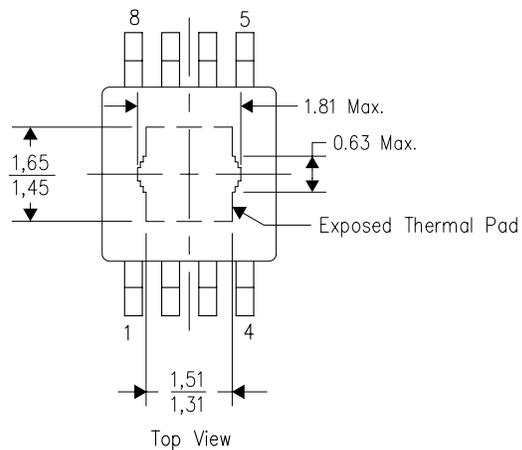
PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

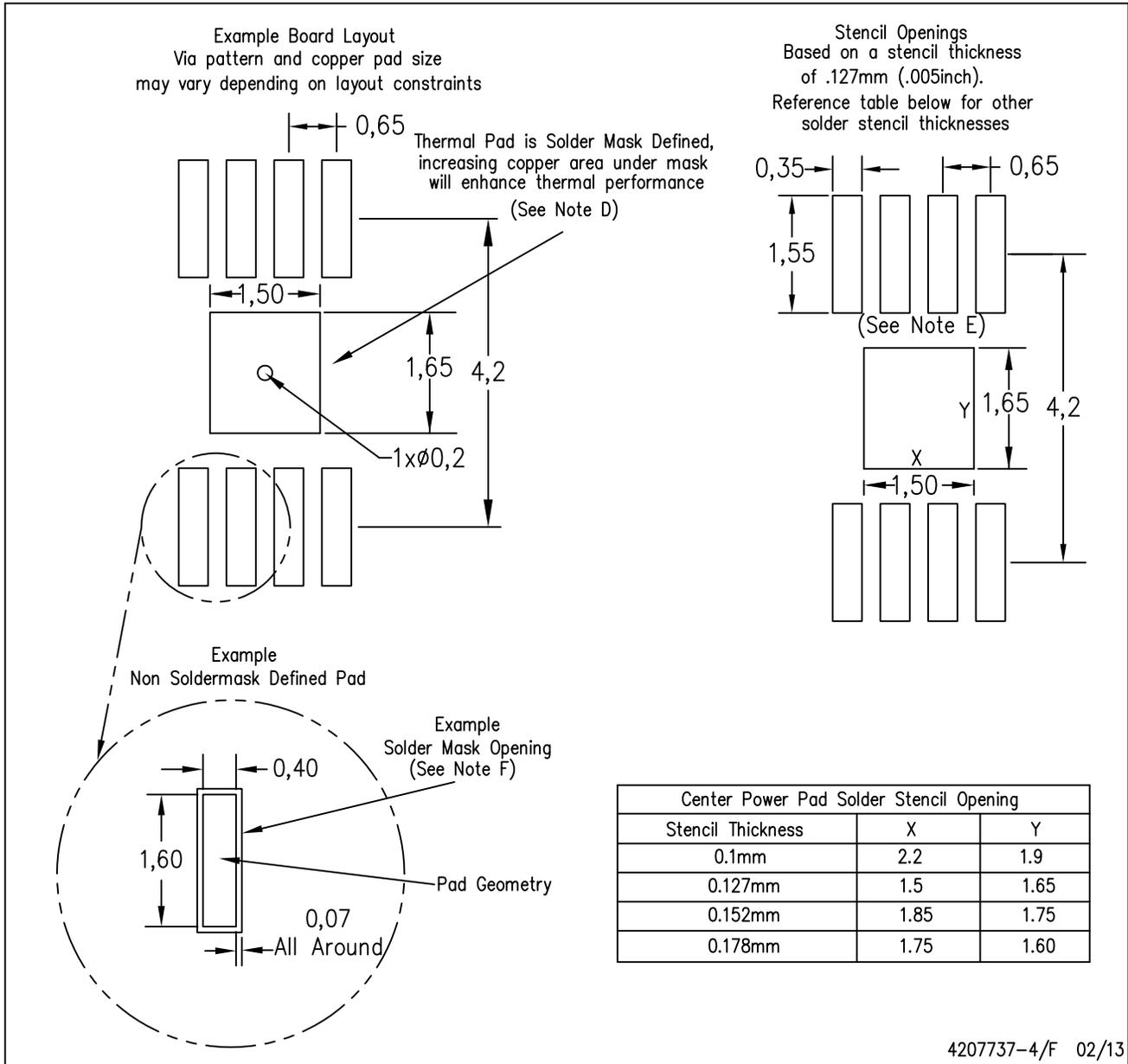


Exposed Thermal Pad Dimensions

4206323-5/1 12/11

NOTE: All linear dimensions are in millimeters

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- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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